



NAN YA PLASTICS CORPORATION
ELECTRONIC MATERIALS DIVISION.
COPPER CLAD LAMINATE DEPARTMENT

Glass cloth base epoxy resin
Flame retardant copper clad laminate

NO. 201. TUNG HWA N. ROAD,
TAIPEI, TAIWAN.

NP-175FR

■ FEATURES

- Dicy-Free & Low C.T.E
- Lead-Free Compatible
- Excellent dimensional stability and through-hole reliability
- Superior CAF-Resistance (Anti-migration)
- High luminance of multi-functional epoxy contrast with copper for A.O.I
- IPC-4101B/99

■ PERFORMANCE LIST

| Characteristics | | Unit | Conditioning | Typical Values | SPEC | Test Method |
|----------------------------------|--------|-------------------|-----------------------------|---------------------------------------|-----------------|-------------|
| Volume resistivity | | MΩ-cm | C-96/35/90 | $5 \times 10^9 \sim 5 \times 10^{10}$ | $10^6 \uparrow$ | 2.5.17 |
| Surface resistivity | | MΩ | C-96/35/90 | $5 \times 10^8 \sim 5 \times 10^9$ | $10^4 \uparrow$ | 2.5.17 |
| Permittivity 1MHZ | | - | C-24/23/50 | 4.6-4.8 | 5.4 ↓ | 2.5.5.9 |
| Permittivity 1GHZ | | - | C-24/23/50 | 4.2-4.4 | - | 2.5.5.9 |
| Loss Tangent 1MHZ | | - | C-24/23/50 | 0.016-0.020 | 0.035 ↓ | 2.5.5.9 |
| Loss Tangent 1GHZ | | - | C-24/23/50 | 0.014-0.016 | - | 2.5.5.9 |
| Arc resistance | | SEC | D-48/50+D-0.5/23 | 120 ↑ | 60 ↑ | 2.5.1 |
| Dielectric breakdown | | KV | D-48/50 | 60 ↑ | 40 ↑ | 2.5.6 |
| Moisture absorption | | % | D-24/23 | 0.05-0.10 | 0.35 ↓ | 2.6.2.1 |
| Flammability | | - | C-48/23/50 | 94V0 | 94V0 | UL94 |
| Peel strength 1 oz | | lb/in | 288°C x 10" solder floating | 8-10 | 6 ↑ | 2.4.8 |
| Thermal stress | | SEC | 288°C x 10" solder dipping | 600 ↑ | 10 ↑ | 2.4.13.1 |
| Pressure cooker (2 atm 120°C) | 1/2 hr | SEC | 288°C dipping | 600 ↑ | N/A | - |
| | 1 hr | SEC | 288°C dipping | 600 ↑ | N/A | - |
| | 2 hr | SEC | 288°C dipping | 600 ↑ | N/A | - |
| Flexural strength | LW | N/mm ² | A | 480-550 | 415 ↑ | 2.4.4 |
| | CW | N/mm ² | A | 415-480 | 345 ↑ | 2.4.4 |
| Dimensional stability X-Y axis | | % | E-0.5/170 | 0.005-0.030 | 0.050 ↓ | 2.4.39 |
| Coefficient of thermal expansion | | | | | | |
| Z-axis before Tg | | ppm/°C | TMA | 40-60 | 60 ↓ | 2.4.24 |
| Z-axis after Tg | | ppm/°C | TMA | 250-270 | 300 ↓ | |
| 50-260°C | | % | TMA | 3.0% | 3.5% ↓ | |
| Glass transition temp | | °C | DMA | 185 | 150 ↑ | 2.4.25 |
| T260 | | min | TMA | >60 | 30 ↑ | 2.4.24.1 |
| T288 | | min | TMA | >20 | 5 ↑ | 2.4.24.1 |
| Td (5% Weight Loss) | | °C | TGA, 10°C/min | 351 | 325 ↑ | - |

NOTE:

The average value in the table refers to samples of .062" 1/1.
Test method per IPC-TM-650

Data shown are nominal values for reference only.



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Glass cloth base epoxy resin
Flame retardant copper clad laminate

NO. 201. TUNG HWA N. ROAD,
TAIPEI, TAIWAN.

NP-175FTL

■ FEATURES

- Dicy-Free & Low C.T.E
- Lead-Free Compatible
- Excellent dimensional stability and through-hole reliability
- Superior CAF-Resistance (Anti-migration)
- High luminance of multi-functional epoxy contrast with copper for A.O.I
- IPC-4101B/99

■ PERFORMANCE LIST

| Characteristics | Unit | Conditioning | Typical Values | SPEC | Test Method |
|----------------------------------|--------|----------------------------|----------------------|-------------------|-------------|
| Volume resistivity | MΩ-cm | C-96/35/90 | 5.0 x10 ⁹ | 10 ⁶ ↑ | 2.5.17 |
| Surface resistivity | MΩ | C-96/35/90 | 5.0 x10 ⁸ | 10 ⁴ ↑ | 2.5.17 |
| Permittivity 1 MHZ | - | C-24/23/50 | 4.4-4.6 | 5.4 ↓ | 2.5.5.9 |
| Permittivity 1 GHZ | - | C-24/23/50 | 3.9-4.1 | - | 2.5.5.9 |
| Loss Tangent 1 MHZ | - | C-24/23/50 | 0.016-0.020 | 0.035 ↓ | 2.5.5.9 |
| Loss Tangent 1 GHZ | - | C-24/23/50 | 0.012-0.014 | - | 2.5.5.9 |
| Arc resistance | SEC | D-48/50+D-0.5/23 | 120 ↑ | 60 ↑ | 2.5.1 |
| Dielectric breakdown | KV | D-48/50 | 60 ↑ | 40 ↑ | 2.5.6 |
| Moisture absorption | % | D-24/23 | 0.20-0.30 | 0.35 ↓ | 2.6.2.1 |
| Flammability | - | C-48/23/50 | 94V0 | 94V0 | UL94 |
| Peel strength 1 oz | lb/in | 288°C x10" solder floating | 8-10 | 6 ↑ | 2.4.8 |
| Thermal stress | SEC | 288°C solder dipping | 600 ↑ | 10 ↑ | 2.4.13.1 |
| Glass transition temp | °C | DMA | 185 | 150 ↑ | 2.4.25 |
| Dimensional stability X-Y axis | % | E 4/105 | 0.01-0.03 | 0.05 ↓ | 2.4.39 |
| Coefficient of thermal expansion | | | | | |
| Z-axis before Tg | ppm/°C | TMA | 40-60 | 60 ↓ | 2.4.24 |
| Z-axis after Tg | ppm/°C | TMA | 250-270 | 300 ↓ | |
| 50-260°C | % | TMA | 3.0% | 3.5% ↓ | |
| T260 | min | TMA | >60 | 30 ↑ | 2.4.24.1 |
| T288 | min | TMA | >20 | 5 ↑ | 2.4.24.1 |
| Td (5% Weight Loss) | °C | TGA, 10°C/min | 351 | 325 ↑ | - |

NOTE:

The average value in the table refers to samples of .020" 1/1.

Test method per IPC-TM-650

Data shown are nominal values for reference only.

■ CONSTRUCTION:

| THICKNESS mm mil | | CONSTRUCTION | | THICKNESS mm mil | | CONSTRUCTION | |
|--------------------------|----|--------------|---------|--------------------------|----|---------------|---------|
| 0.05 | 2 | 106 | 1 PLY | 0.35 | 14 | 7628 | 2 plies |
| 0.08 | 3 | 2112 | 1PLY | 0.38 | 15 | 7628 | 2 plies |
| 0.10 | 4 | 1080 | 2 plies | 0.45 | 18 | 7628x2+1080x1 | |
| 0.11 | 4 | 2116 | 1 ply | 0.50 | 20 | 7628 | 3 plies |
| 0.13 | 5 | 1080 | 2 plies | 0.53 | 21 | 7628 | 3 plies |
| 0.13sp | 5 | 2116 | 1 ply | 0.60 | 24 | 7628 | 3 plies |
| 0.15 | 6 | 1506 | 1 ply | 0.77 | 31 | 7628 | 4 plies |
| 0.16 | 6 | 2112 | 2 plies | 0.8 | 32 | 7628 | 4 plies |
| 0.21 | 8 | 7628 | 1 ply | 0.9 | 36 | 7628 | 5 plies |
| 0.26 | 10 | 2116 | 2 plies | 1.0 | 39 | 7628 | 5 plies |
| 0.30 | 12 | 2116 | 3 plies | 1.1 | 43 | 7628 | 6 plies |
| 0.30sp | 12 | 1506 | 2 plies | 1.2 | 47 | 7628 | 6 plies |

• 1.2, 1.1, 1.0, 0.9 0.77 mm THICKNESS INCLUDE CLADDING, ALL OTHERS EXCLUDE CLADDING

■ PRODUCT SIZE & THICKNESS

| THICKNESS INCH (mm) | COPPER CLADDING OZ (µm) | | SIZE INCH mm | | THICKNESS TOLERANCE |
|----------------------------------|----------------------------|-----------|--|--|-----------------------------|
| 0.004 (0.1) to 0.039 (1.0) | Q (9) | 3.0 (105) | 48.8 x 36.6 1240 x 0930 48.8 x 40.5 1240 x 1030 48.8 x 42.5 1240 x 1080 | | IPC-4101B SPEC CLASS C/M |
| | T (12) | 4.0 (140) | | | |
| | H (17) | 5.0 (175) | | | |
| | 1.0 (35) | 6.0 (210) | | | |
| | 2.0 (70) | | | | |

- Keeping the core and prepreg in the same grain direction is crucial to ensure the flatness of multilayer boards.

Grain direction is shown on the Certificate of Conformance.

- We recommend to evaluate the drilling property.
- Different oxide treatment may result in variations in the heat resistance properties of the laminates after processing. Pre-production batch runs are recommended to ensure compatibility of materials with chemicals.



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**Glass cloth base epoxy resin
Flame retardant prepreg**

NO. 201. TUNG HWA N. ROAD,
TAIPEI, TAIWAN.

NP-175FB PREPREG

■ FEATURES

- Dicy-Free & Low C.T.E
- Lead-Free Compatible
- Excellent dimensional stability and through-hole reliability
- Superior CAF-Resistance (Anti-migration)
- We recommend to evaluate the drilling property.
- Different oxide treatment may result in variations in the heat resistance properties of the laminates after processing.
- Pre-production batch runs are recommended to ensure compatibility of materials with chemicals.
- High luminance of multi-functional epoxy contrast with cop-
- per for A.O.I
- IPC-4101B/99

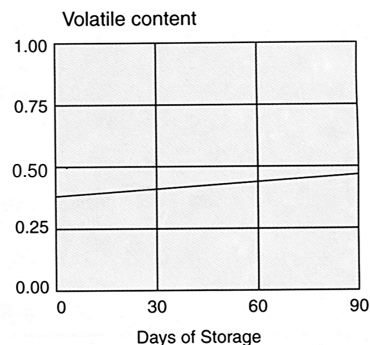
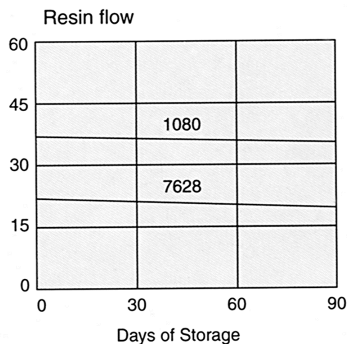
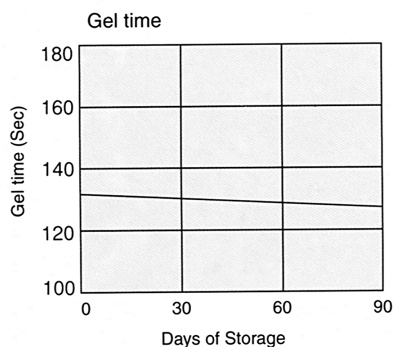
■ PERFORMANCE LIST

Specification: IPC-4101B is applicable

Data shown are nominal values for reference only. (Remained Copper 70-80%)

| Glass style | RC% | RF% | GT sec (170°C) | VC% | After Pressed Thickness (per ply) | |
|-------------|--------|--------|-------------------|-------|-----------------------------------|------------|
| | | | | | mm | Mil |
| 7628HR | 52 ± 3 | 31 ± 5 | 130 ± 20 | 1.5 ↓ | 0.199 ± 0.01 | 7.8 ± 0.4 |
| 7628MR | 49 ± 3 | 28 ± 5 | | | 0.191 ± 0.01 | 7.5 ± 0.4 |
| 7628 | 45 ± 3 | 21 ± 5 | | | 0.181 ± 0.01 | 7.1 ± 0.4 |
| 1506MR | 54 ± 3 | 34 ± 5 | | | 0.160 ± 0.01 | 6.3 ± 0.4 |
| 1506 | 50 ± 3 | 27 ± 5 | | | 0.150 ± 0.01 | 6.0 ± 0.4 |
| 2116HR | 60 ± 3 | 40 ± 5 | | | 0.132 ± 0.01 | 5.2 ± 0.4 |
| 2116MR | 56 ± 3 | 34 ± 5 | | | 0.118 ± 0.01 | 4.6 ± 0.4 |
| 2116 | 52 ± 3 | 28 ± 5 | | | 0.105 ± 0.01 | 4.1 ± 0.4 |
| 2313 | 57 ± 3 | 35 ± 5 | | | 0.090 ± 0.01 | 3.5 ± 0.4 |
| 2113 | 58 ± 3 | 35 ± 5 | | | 0.090 ± 0.01 | 3.5 ± 0.4 |
| 2112 | 62 ± 3 | 35 ± 5 | | | 0.079 ± 0.008 | 3.1 ± 0.3 |
| 1080HR | 70 ± 3 | 50 ± 5 | | | 0.076 ± 0.008 | 3.0 ± 0.3 |
| 1080MR | 67 ± 3 | 45 ± 5 | | | 0.071 ± 0.008 | 2.8 ± 0.3 |
| 1080 | 64 ± 3 | 40 ± 5 | | | 0.064 ± 0.008 | 2.5 ± 0.3 |
| 106 | 70 ± 3 | 42 ± 5 | | | 0.048 ± 0.008 | 1.91 ± 0.3 |

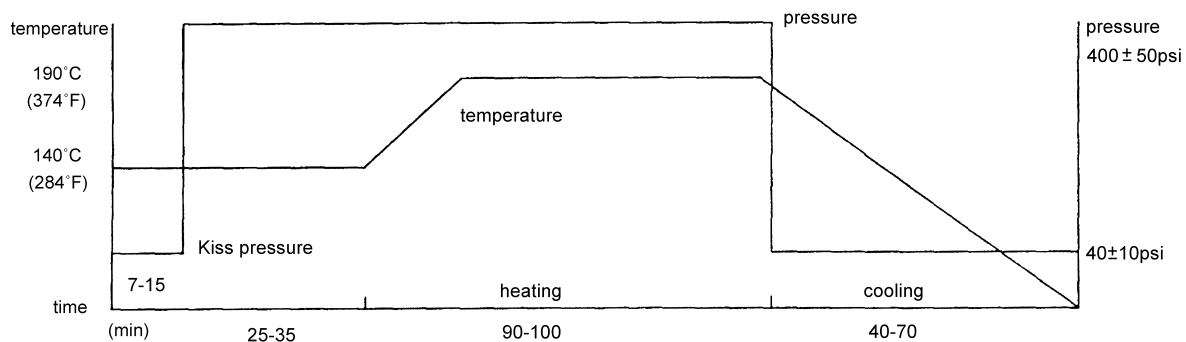
Storage Stability



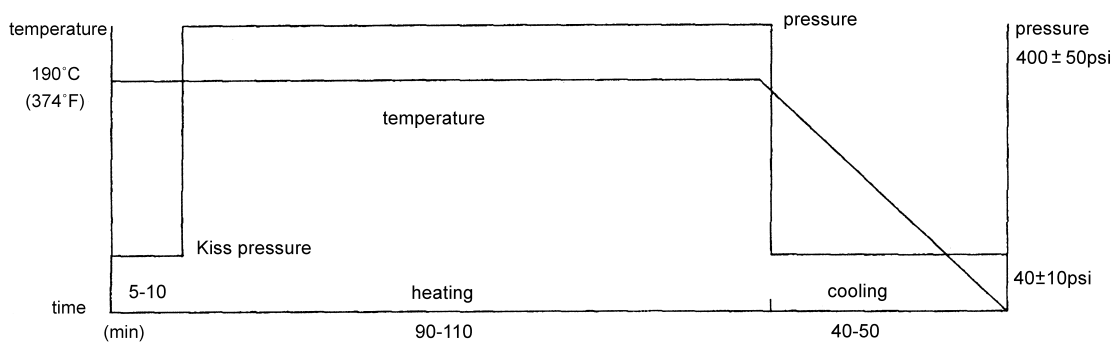
Storage Condition: 20°C, 50% RH for 3 months
: Max 5°C for 6 months

Recommended press cycles:

A:2T2P (2 temperature step/2 pressure step)



B:1T2P (1 temperature step/2 pressure step)



Suggestions:

1. Heating rate of material between 70°C and 140°C
1-3°C/min is acceptable.
1.5-2.5°C/min would be better.
2. Temperature of material over 170°C must be held for at least 60min. to allow epoxy resin to fully cure.
3. The pressure should be kept below 100psi during cooling to ambient temperature.
4. Cooling rate of material should be kept under 2.5°C/min when the temperature of material is over 100°C, in order to avoid introducing twist.